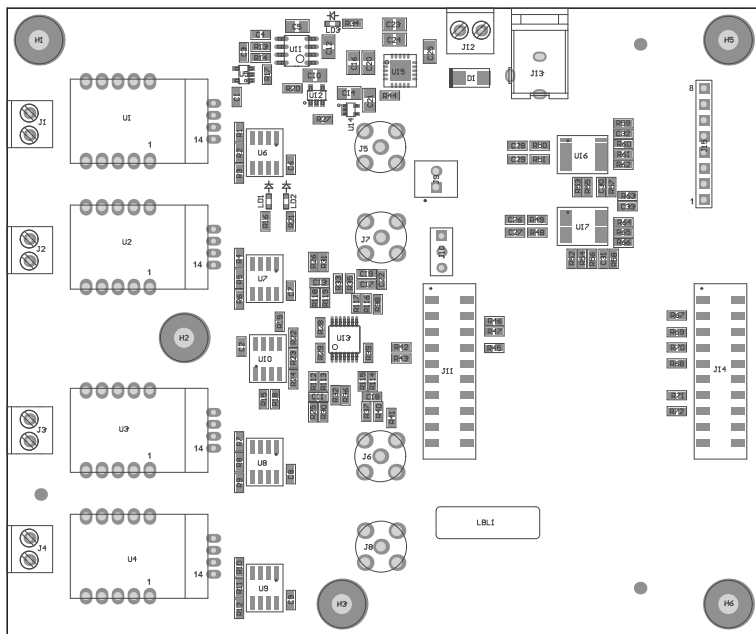
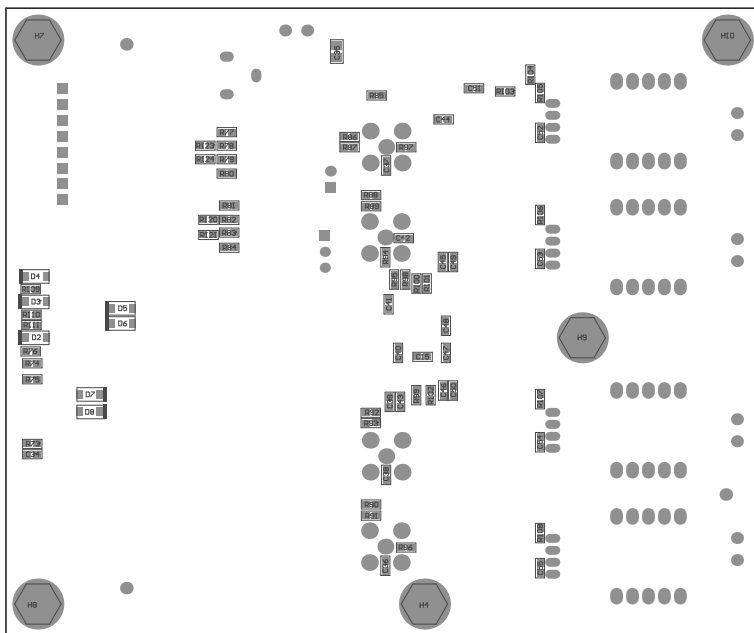


- z22 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PCB schematic.  
 z23 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.  
 z24 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.  
 z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00208	REV: E2	SUN REV: Not In VersionControl
IGNORE -> M5 Assembly Top			
PLOT NAME = Top Assembly Drawing	GENERATED : 10/17/2014 6:32:53 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00208	REV: E2	SUN REV: Not In VersionControl
	IGNORE ->		M6 Assembly Bottom
PLOT NAME = Bottom Assembly Drawing	GENERATED : 10/17/2014 6:32:54 PM	TEXAS INSTRUMENTS	

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